Product Change Notification

Change Notification #:	**118897-00**
Change Title:	**Select Boxed Intel® Xeon® Processors, PCN 118897-00, Product Material, Thermal Solution Update**
Date of Publication:	**February 10, 2022**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material	March 13, 2022

Description of Change to the Customer:

Intel® Xeon® E boxed processors are transitioning from the DHA-A (E97378-003) thermal solution to the DHA-X (K69237-001) thermal solution. The DHA-X is a newer generation thermal solution with a better supply line and has equivalent thermal performance, size, and installation process as the DHA-A. Boxed product received may contain the DHA-A until existing inventories have been depleted.

Current Thermal Solution (DHA-A)

New Thermal Solution (DHA-X)

Customer Impact of Change and Recommended Action:

No customer impact expected as thermal performance, size and installation processes are the same.

Customers may see a mix of products until inventory has been depleted. Customers may also receive post-conversion material before the above target date if the current inventory is depleted sooner.

Please contact your local Intel Field Sales representative if you have any further questions about this End of Life notice.

Products Affected/Intel Ordering Codes:

Marketing Name	Stepping	MM#	Product Code	Spec Code	Platform
Boxed Intel® Xeon® Processor E3-1270 v6	B0	954318	BX80677E31270V6	S R326	SERVER
Boxed Intel® Xeon® Processor E3-1240 v6	B0	954319	BX80677E31240V6	S R327	SERVER
Boxed Intel® Xeon® Processor E3-1230 v6	B0	954320	BX80677E31230V6	S R328	SERVER
Boxed Intel® Xeon® Processor E3-1275 v6	B0	954321	BX80677E31275V6	S R32A	WORKSTATION
Boxed Intel® Xeon® Processor E3-1245 v6	B0	954323	BX80677E31245V6	S R32B	WORKSTATION
Boxed Intel® Xeon® Processor E3-1220 v6	B0	954324	BX80677E31220V6	S R329	SERVER
Boxed Intel® Xeon® Processor E3-1225 v6	B0	954325	BX80677E31225V6	S R32C	WORKSTATION
Boxed Intel® Xeon® E-2124 Processor	U0	973772	BX80684E2124	S R3WQ	SERVER
Boxed Intel® Xeon® E-2176G Processor	U0	973773	BX80684E2176G	S R3WS	WORKSTATION
Boxed Intel® Xeon® E-2136 Processor	U0	973774	BX80684E2136	S R3WW	SERVER
Boxed Intel® Xeon® E-2146G Processor	U0	974864	BX80684E2146G	S R3WT	WORKSTATION
Boxed Intel® Xeon® E-2124G Processor	U0	977233	BX80684E2124G	S R3WL	WORKSTATION
Boxed Intel® Xeon® E-2134 Processor	U0	977235	BX80684E2134	S R3WP	SERVER
Boxed Intel® Xeon® E-2174G Processor	U0	977244	BX80684E2174G	S R3WN	WORKSTATION
Boxed Intel® Xeon® E-2226G Processor	U0	999JMG	BX80684E2226G	S RF7F	WORKSTATION
Boxed Intel® Xeon® E-2236 Processor	U0	999JMH	BX80684E2236	S RF7G	SERVER
Boxed Intel® Xeon® E-2224 Processor	U0	999JMJ	BX80684E2224	S RFAV	SERVER
Boxed Intel® Xeon® E-2224G Processor	U0	999JML	BX80684E2224G	S RFAW	WORKSTATION
Boxed Intel® Xeon® E-2234 Processor	U0	999JMM	BX80684E2234	S RFAX	SERVER

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
February 10, 2022	00	Originally Published PCN

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